

曜凌光電股份有限公司

 住址: 42878 台中市大雅区科雅路 25 號 5F
 WEB: <u>http://www.Raystar-Optronics.com</u>

 5F., No.25, Keya Rd., Daya Dist., Taichung
 E-mail: <u>sales@raystar-optronics.com</u>

 City 428, Taiwan
 Tel:886-4-2565-0761
 Fax: 886-4-2565-0760

RX12864C2-FHW

SPECIFICATION

CUSTOMER:

APPROVED BY

PCB VERSION

DATE

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
Release DATE:			



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2009/07/14		First issue
А	2012/12/07		Modify Backlight
			Information
			Modify VOP
В	2013/01/16		Correct Vo-Vss
С	2014/07/29		Remove IC
			information



Contents

- 1.General Specification
- 2. Module Classification Information
- **3.Interface Pin Function**
- 4.Contour Drawing
- **5.Optical Characteristics**
- 6. Absolute Maximum Ratings
- **7.**Electrical Characteristics
- 8.Backlight Information
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13.Recommendable Storage



1.General Specification

The Features is described as follow:

- Module dimension: 55.2x 39.8 x 6.5 (max.) mm
- View area: 45.2 x 27.0 mm
- Active area: 40.92 x 24.28 mm
- Number of dots: 128 x 64
- Dot size: 0.28 x 0.34 mm
- Dot pitch: 0.32 x 0.38 mm
- LCD type: FSTN Positive Transflective
- Duty: 1/64 , 1/9 Bias
- View direction: 6 o'clock
- Backlight Type: LED White
- IC: ST7565P



2.Module Classification Information

<u>R</u>	<u>X</u>	<u>12864</u>	<u>C2</u>	_	<u>F</u>	<u>H</u>	W
1	2	3	4		5	6	\bigcirc

Item		C	Descriptio	on	
1	R : Raystar O	ptronics Inc.			
2	Display	C: Character Type,		T:TAB Type	
2	Display	G: Graphic Type		X:COG Type	
3	Display Font :	128 * 64 dot			C^{-}
4	Serials code :	Γ		Γ	
		$P \rightarrow TN$ Positive, Gray			egative, Blue
		N→TN Negative,			egative, Black
		L→VA Negative			egative (Double film)
_		$H \rightarrow HTN$ Positive, Gray		F→FSTN Po	
5	LCD	I→HTN Negative, Black		K→FSC Neg	
		U→HTN Negative, Blue		S→FSC Pos	
		B→STN Negative, Blue			gative, Black
		G→STN Positive, Gray			egative, Black
		$Y \rightarrow STN$ Positive, Yellow	Green		egative, Black
	Delerizer	A : Reflective, N.T, 6:00			ctive, W.T,12:00
	Polarizer Type,	D : Reflective, N.T, 12:0			tive, U.T,6:00
	Type,	G : Reflective, W. T, 6:00			otive, U.T.12:00
6	Temperature	J: Reflective, W. T, 12:0			ssive, N.T,6:00
0	range,	0 : Reflective, U. T, 6:00			sive, N.T, 12:00
		3 : Reflective, U. T, 12:0			sive, W. T, 6:00
	View direction	B : Transflective, N.T,6:0 E : Transflective, N.T.12			sive, W.T,12:00
	unection	H : Transflective, W.T.6:			sive, U. T, 6:00 sive, U.T,12:00
		$N \rightarrow$ Without backlight	00 W→LE[$H \rightarrow LED$, High light White
		$P \rightarrow EL$, Blue		, Amber	$S \rightarrow LED$, Full color
		$T \rightarrow EL, Green$	R→LED		$J \rightarrow DIP LED, Blue$
_		$D \rightarrow EL$, White), Orange	$K \rightarrow DIP LED, White$
7	Backlight	$M \rightarrow EL$, Yellow Green	B→LED		$E \rightarrow DIP LED, Yellow$
		$F \rightarrow CCFL$, White		, Dual color	L→DIP LED, Amber
		Y→LED, Yellow Green		, Full color	I→DIP LED, Red
		G→LED, Green			



3.Interface Pin Function

Pin No.	Symbol	Level			Desci	ription		
1	IRS	I	adjustm IRS = "H IRS = "L	l": Use the inte .": Do not use t d by an extern	rnal resisto he internal	ors resistors.	The V0 volt	age level is
2	/HPM	I	liquid cr <u>y</u> /HPM =	This is the power control terminal for the power supply circuit for quid crystal drive. HPM = "H": Normal mode HPM = "L": High power mode This is the parallel data input/serial data input switch terminal.				
3	P/S	I	P/S = "H P/S = "L The follo P/S "H" "L" When P. /RD (E)	he parallel data I": Parallel data I": Serial data in owing applies of Data/Command A0 /S = "L", D0 to and /WR (R/W fial data input,	a input. nput. lepending Data D0 to D7 SI (D7) D5 fixed) are fixed	on the P/S Read/Write /RD, /WR Write only "H". to either "H	status: Serial Clock X SCL (D6) H" or "L".	
4	C86		This is tl C86 = "ŀ	he MPU interfa H": 6800 Series -": 8080 Series	ce selections MPU inte	on pin. rface.		
5	VR	I	VSS and IRS = "L	voltage regulate d V0 through a ." : the V0 volta d" : the V0 volta	resistive v ige regulat	oltage dividor of the second sec	der. resistors ar	e not used.
6~10	V0~V4	Power Supply	This is a	a multi-level po	wer supply	for the liqu	uid crystal d	rive.
11	VRS	Power Supply		he internal-out		power sup	ply for the L	.CD power



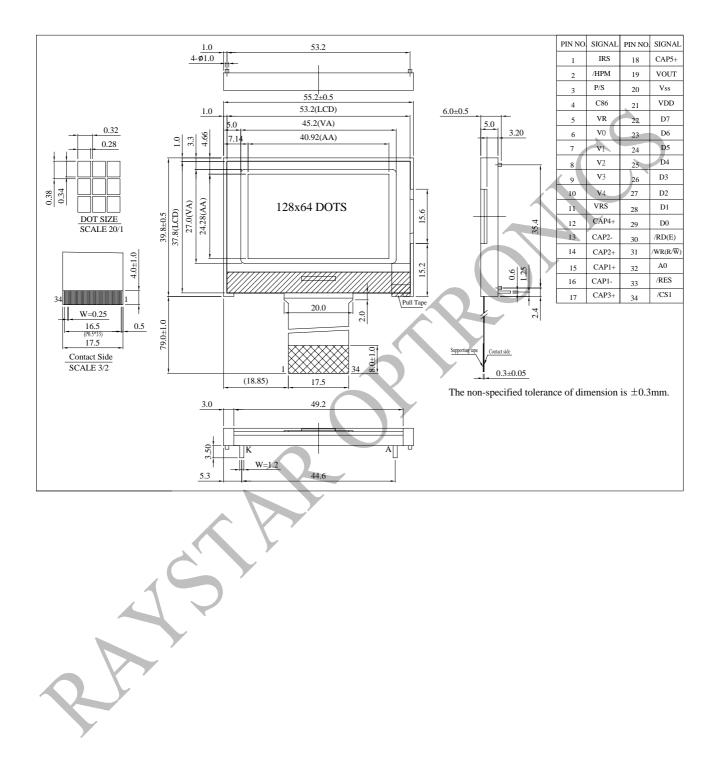
12	CAP4+	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
13	CAP2-	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2P terminal.
14	CAP2+	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
15	CAP1+	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
16	CAP1-	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.
17	CAP3+	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
18	CAP5+	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
19	VOUT	0	DC/DC voltage converter. Connect a capacitor between this terminal and vss or VDD
20	VSS	Power Supply	Ground
21	VDD	Power Supply	Power supply
22~29	D7~D0	I/O	Data bus line
30	/RD(E)	5	 When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the 8080 MPU and is LOW-active. The data bus is in an output status when this signal is "L". When connected to 6800 series MPU, this pin is treated as the "E" signal of the 6800 MPU and is HIGH-active. This is the enable clock input terminal of the 6800 Series MPU.
31	/WR(RW)	I	 When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the 8080 MPU and is LOW-active. The signals on the data bus are latched at the rising edge of the /WR signal. When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the 6800 MPU and decides the access type : When R/W = "H": Read. When R/W = "L": Write.



32	A0	I	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command. A0 = "H": Indicates that D0 to D7 are display data. A0 = "L": Indicates that D0 to D7 are control data.
33	/RES	I	When RES is set to "L", the setting are initialized.
34	/CS1	I	This is the chip select signal.



4.Contour Drawing



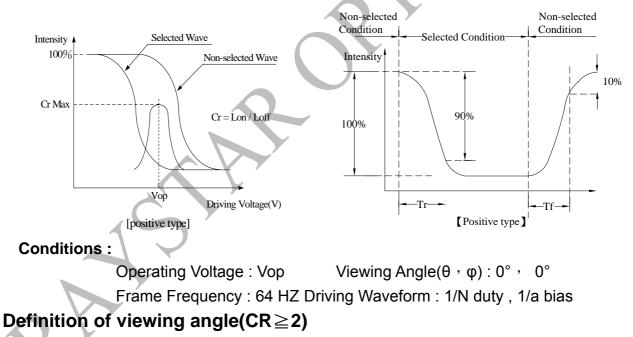


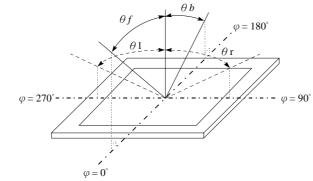
5.Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR≧2	0	_	30	ψ= 180°
	θ	CR≧2	0		60	ψ= 0°
view Angle	θ	CR≧2	0	_	45	ψ= 90°
	θ	CR≧2	0	_	45	ψ= 270°
Contrast Ratio	CR		_	5		
Deenenee Time	T rise		_	200	300	ms
Response Time	T fall	_		250	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)







6.Absolute Maximum Ratings

ltem	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Power Supply Voltage	VDD	-0.3		3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	-	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3	\bigcirc	V 0+0.3	V



7.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Мах	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}		2.7	3.0	3.3	V
		Ta=-20 ℃		_		V
Supply Voltage For LCM	VOP	Ta=25 ℃	9.4	9.6	9.8	V
		Ta=70 ℃	_	_	-	V
Input High Volt.	V _{IH}	_	0.8 V _{DD}		V _{DD}	V
Input Low Volt.	V _{IL}		Vss	-	$0.2 V_{DD}$	V
Output High Volt.	V _{OH}	-	0.8 V _{DD}		V _{DD}	V
Output Low Volt.	V _{OL}	-	Vss	_	$0.2V_{DD}$	V
Supply Current(No	I		×	0.40	10	
include LED Backlight)	I _{DD}	V _{DD} =3.0V		0.49	1.0	mA

NOTE 1: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

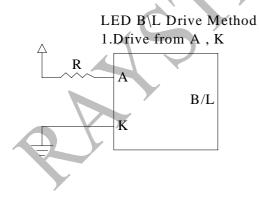
8.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	48	60	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	v	
Reverse Voltage	VR	_	_	5	v	-
Luminance	N/	600	050		CD/M2	ILED=48mA
(Without LCD)	IV	680	850		CD/W	ILED=48MA
LED Life Time					Y	ILED≦48mA
(For Reference	_	—	50000		Hr.	25℃,50-60%RH,
only)				X		(Note 1)
Color	White)		

Note: The LED of B/L is drive by current only ; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.





9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test							
Test Item	Content of Test	Test Condition	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1				
High Temperature/ Humidity storage	The module should be allowed to stand at $60^{\circ}C$,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



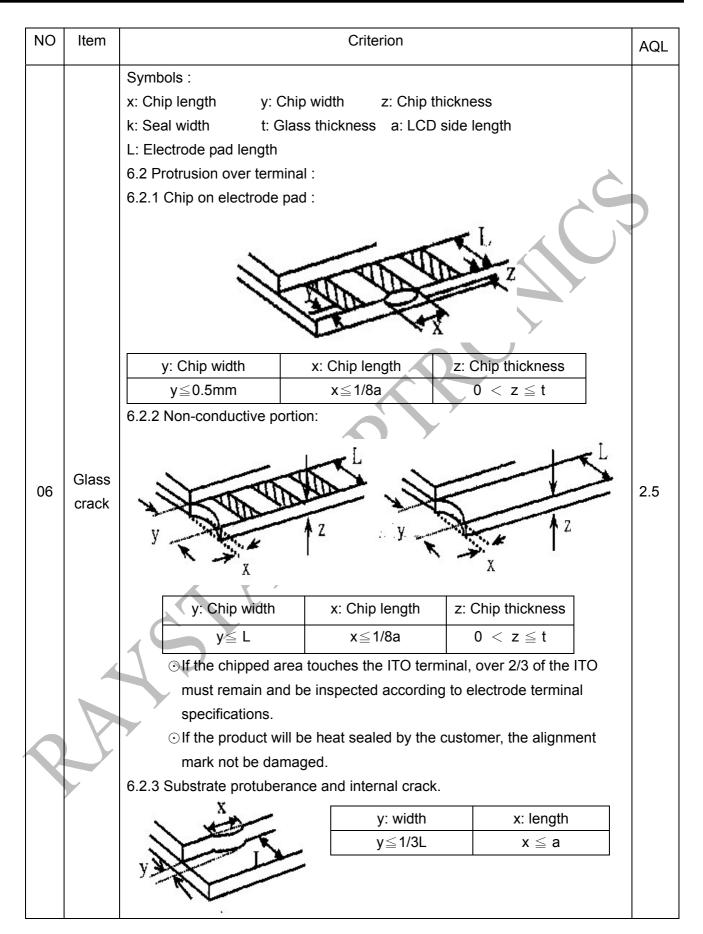
10.Inspection specification

NO	Item			Criterion		AQL
		1.1 Missing verti defect.	ical, horizo	ontal segment, seg	ment contrast	
		1.2 Missing char	racter , do	t or icon.		
	Electrical	1.3 Display malf	unction.			
01	Testing	1.4 No function	or no displ	lay.	. C	0.65
	looung		-	exceeds product sp	pecifications.	\mathbf{C}
		1.6 LCD viewing	•	fect.		
		1.7 Mixed produ	• •			
		1.8 Contrast def				
	Black or white		•	on display ≤ 0.25	mm, no more than	
02	spots on LCD	three white c				2.5
	(display only)	2.2 Densely spa	ced: No m	ore than two spots	s or lines within 3mm	
		3.1 Round type				
		Φ=(x + y) /				
		$\Psi^{-}(\chi \cdot y)$		SIZE	Acceptable Q TY	
		⊢⊸––>∩ ––⊸		Φ≦0.10	Accept no dense	2.5
			v	0.10<Φ≦0.20	2	
	LCD black		T ⊢	0.20<Φ≦0.25	1	
	spots, white			0.25<Φ	0	
03	spots,	3.2 Line type : (/	Ac followin	a drawing)		
	contamination	5.2 Line type . (/		Width	Acceptable Q TY	
	(non-display)	(★	Length	Width W≦0.02	Accept no dense	
			 L≦3.0	0.02 <w≦0.02< td=""><td>Accept no dense</td><td></td></w≦0.02<>	Accept no dense	
		– ≯ I <u>L</u> H4–	L≦0.0 L≦2.5	0.03 <w≦0.05< td=""><td>- 2</td><td>2.5</td></w≦0.05<>	- 2	2.5
			L=2.0	0.05 <w 0.05<w< td=""><td>As round type</td><td></td></w<></w 	As round type	
				0.00 < 11	As found type	
	Ϋ́,					
N						
		If bubbles are vi	sible,	Size Φ	Acceptable Q TY	
	 .	judge using blac		Ф≦0.20	Accept no dense	
04	Polarizer	specifications, n	ot easy	$0.20 \! < \! \Phi \! \le \! 0.50$	3	2.5
	bubbles	to find, must che	eck in	$0.50 \! < \! \Phi \! \le \! 1.00$	2	
		specify direction	I.	1.00<Φ	0	
				Total Q TY	3	



NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD black	spots, white spots, con	tamination	
		Symbols Define:x: Chip lengthy:k: Seal widtht: CL: Electrode pad length6.1 General glass chip	Chip width z: Chip Glass thickness a: LCE	thickness D side length	P
06	Chipped glass		y: Chip width Not over viewing area Not exceed 1/3k e chips, x is total length o	x: Chip length $x \le 1/8a$ $x \le 1/8a$ of each chip.	2.5
2		6.1.2 Corner crack: z: Chip thickness $Z \le 1/2t$	y: Chip width Not over viewing area	y x: Chip length x≦1/8a	
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a	
		\odot If there are 2 or more	e chips, x is the total leng	gth of each chip.	





RAYSTAR

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
08	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5
00	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	0.65
		9.2 Bezel must comply with job specifications.	0.00
		10.1 COB seal may not have pinholes larger than 0.2mm or	
		contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	
		10.3 The height of the COB should not exceed the height	2.5
		indicated in the assembly diagram.	0.65
		10.4 There may not be more than 2mm of sealant outside the	
		seal area on the PCB. And there should be no more than	2.5
		three places.	
		10.5 No oxidation or contamination PCB terminals.	
10	PCB COB	10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts,	2.5
		missing parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product	
		characteristic chart.	
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	0.65
		screw hold pad, make sure it is smoothed down.	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
		X	2.5
		X * Y<=2mm2	
		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections, oxidation	2.5
11	Soldering	or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.12.3 No contamination, solder residue or solder balls on product.	0.65
		12.3 No containination, solder residue of solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits.	2.5 2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
12	General	pin must be present or look as if it cause the interface pin to sever.12.6 The residual rosin or tin oil of soldering (component or chip	2.5
	appearance	component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on	
		packaging specification sheet.12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	





11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)



12.Material List of Components for RoHs

1. RAYSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

		-		-		
Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited	100	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm
Above limit	ted value is	set up acco	ording to Re	oHS.		

- 2.Process for RoHS requirement :
 - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320° C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235 \pm 5°C ;

Recommended customer's soldering temp. of connector $: 280^{\circ}$ C, 3 seconds.





13.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

	LCM Sample	e Estimate Feedback Sheet
Module Number :		
1 · Panel Specification :		
1. Panel Type :	Pass	□ NG ,
2. View Direction :	Pass	□ NG ,
3. Numbers of Dots :	Pass	□ NG ,
4. View Area :	Pass	□ NG ,
5. Active Area :	Pass	□ NG ,
6.Operating Temperature :	Pass	□ NG ,
7.Storage Temperature :	Pass	□ NG ,
8.Others :		
2 · Mechanical Specification :		
1. PCB Size :	Pass	□ NG ,
2.Frame Size :	Pass	□ NG ,
3.Materal of Frame :	Pass	□ NG ,
4.Connector Position :	Pass	□ NG ,
5.Fix Hole Position:	Pass	□ NG ,
6.Backlight Position :	Pass	□ NG ,
7. Thickness of PCB :	Pass	□ NG ,
8. Height of Frame to PCB :	Pass	□ NG ,
9.Height of Module :	Pass	□ NG ,
10.Others :	Pass	□ NG ,
3 · <u>Relative Hole Size</u> :		
1.Pitch of Connector :	Pass	□ NG ,
2.Hole size of Connector :	Pass	□ NG ,
3.Mounting Hole size :	Pass	□ NG ,
4.Mounting Hole Type :	Pass	□ NG ,
5.Others:	Pass	□ NG ,
4 · Backlight Specification :		
1.B/L Type:	Pass	□ NG ,
2.B/L Color :	Pass	□ NG ,
3.B/L Driving Voltage (Referer	nce for LED Ty	/pe):□ Pass □ NG ,
4.B/L Driving Current :	Pass	□ NG ,
5.Brightness of B/L :	Pass	□ NG ,
6.B/L Solder Method :	Pass	□ NG ,
7.Others:	Pass	□ NG ,

>> Go to page 2 <<



		Page: 2
Module Number :		
5 · Electronic Characteristics of	of Module :	
1.Input Voltage :	Pass	□ NG ,
2.Supply Current :	Pass	□ NG ,
3.Driving Voltage for LCD :	Pass	□ NG ,
4.Contrast for LCD :	Pass	□ NG ,
5.B/L Driving Method :	□ Pass	□ NG ,
6.Negative Voltage Output :	Pass	□ NG ,
7.Interface Function :	Pass	□ NG ,
8.LCD Uniformity :	Pass	□ NG ,
9.ESD test :	Pass	□ NG ,
10.Others:	Pass	□ NG ,
15	Y	

Sales signature : _____ Customer Signature : _____

|--|